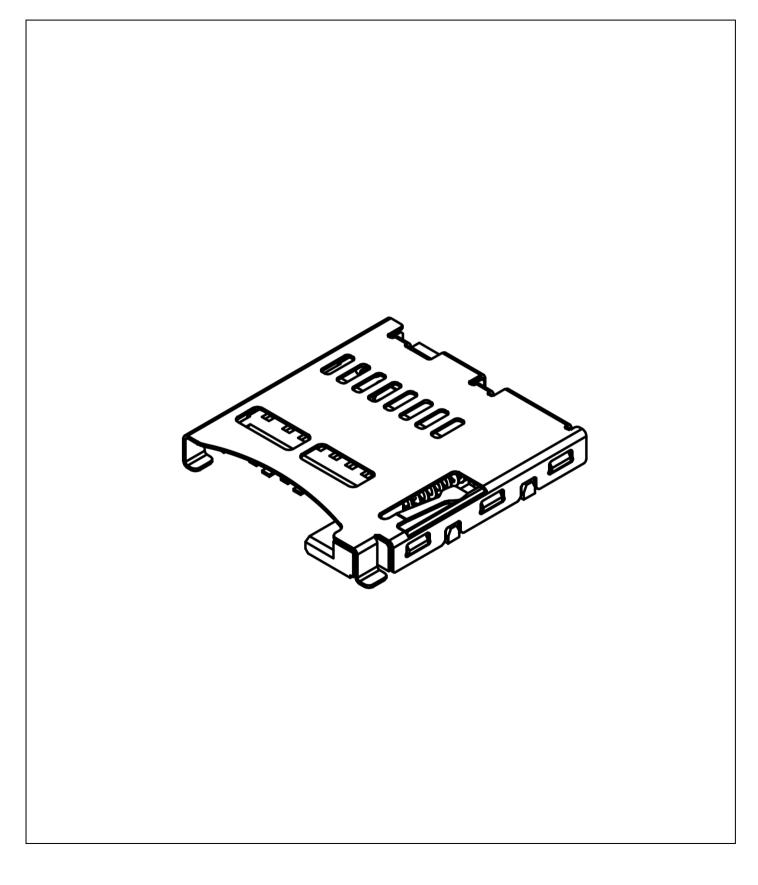
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1.0 SCOPE This specification covers performance, test and quality requirements for the Micro SD Memory Card Connector – card detect normally open – MEM2052 (Push-Push Type, SMT, 1.95mm Profile).								
	CT NAME AND PART NU		IEM2052					
3.0 PRODUC	CTSHAPE, DIMENSIONS	S AND MAT	ERIAL					
Please	e refer to drawings							
4.0 RATING	S							
4.1. Cu	rrent rating	0.5	A AC/DC N	lax.				
4.2. Vo	4.2. Voltage rating 10V AC/DC Max.							
4.3. Operating Temperature Range40°C TO +85°C								

### 5.0 TEST AND MEASUREMENT CONDITIONS

Product is designed to meet electrical, mechanical and environmental performance requirements specified in Paragraph 6.0. All tests are performed in ambient conditions unless otherwise specified.

### 6.0 PERFORMANCE

Item	Test Condition	Requirement
Examination of Product	Visual, dimensional and functional inspection as per quality plan.	Product shall meet requirements of product drawing and specification.



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### 6.1 Electrical Performance

ltem	Test Condition	Requirement
Contact Resistance	Measure and record contact resistance of mated connector using test current of 10mA max and 20 mV open circuit voltage in accordance with EIA-364-6B.	100mΩ max.
Insulation Resistance	Apply 500Volts DC between adjacent contacts of mated connectors for one minute in accordance with EIA-364-21C	1000MΩ min.
Dielectric Strength	Mate connectors and apply 500 V AC for 1 minute between adjacent terminal ground, in accordance with EIA-364-20B.	No Breakdown

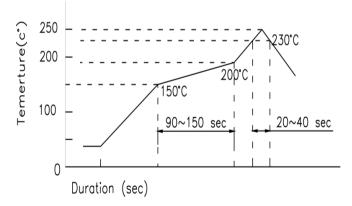
### 6.2 Mechanical Performance

Item	Test Condition	Requirement
Card Retention Force	Pull the card at speed of 25mm/min.	Initial value 0.8N minimum.
Insertion/Ejection Force	Push the card at speed of 25+/- 3mm/minute.	Lock Force: 10N (1.02 kgf) Max. Lock Release Force: 10N (1.02 kgf) Max.
Durability	The connector should be mated and unmated for 10000 cycles with 0.6mm travel at a rate of 25mm/min. In accordance with EIA-364-09.	No evidence of physical damage. Contact Resistance 100mΩ max.
Vibration	Subject mated connectors to 10 to 55 to 10 Hz frequency span over 1 minute at a 1.5mm amplitude. Test to be conducted on 3 mutually perpendicular planes for 15minutes each with 100mA applied and in accordance with EIA-364-28D.	No electrical discontinuity greater than 1 μsec. shall occur. No damage to product. Contact Resistance 100mΩ max.
Mechanical Shock	Subject the part to a 294m/s2 half sine wave acceleration for 11 ms. Three shocks to be applied in each of the X, Y and Z planes and in both directions. A total of 18 shocks. Apply DC 1 mA current during test in accordance with EIA-364-27B.	No electrical discontinuity greater than 1 μsec. shall occur. No damage to product. Contact Resistance 100mΩ max.



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Item	Test Condition	Requirement
Thermal Shock (Temperature cycling)	Mate Connector and perform the following thermal cycle: -55+/-3°C for 30 minutes. +85+/-2°C for 30 minutes. Repeat for 5 cycles in accordance with EIA-364-32.	
Humidity Test	Mate connector and expose to temperature of 40±2°C with 95% RH for 96 hours then place in ambient temperature for 1 to 2 hrs. In accordance with EIA-364-31 method III test condition A.	No evidence of physical damage, discharge, flashes or corrosion in contact areas. Contact Resistance 100mΩ max.
Salt Spray	Subject mated connectors to 35±2°C and 5±1% salt condition for 48hours. Test in accordance with EIA-364-26B.	Insulation Resistance 1000ΜΩ min.
Temperature Life (High)	Subject product to $85\pm2^{\circ}$ C for 96 hours continuously in accordance with EIA-364- 17, method A.	
Solderability	Dip solders tails into molten solder, held at a temperature of 245±5°C for 5±0.5 seconds, in accordance with EIA-364-52.	95% of immersed area must show no voids of pin holes.
Resistance to Reflow Soldering Temp.	Mount connector, place in reflow oven and expose to the temperature profile shown in fig 1.0	No evidence of physical damage o abnormalities adversely affecting performance.







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### 7.0 PRODUCT QUALIFICATION AND TEST SEQUENCE

Test Item		Group							
rest item	A	В	С	D	E	F	G		
Examination of Product	1,7	1,10	1,10	1,5	1,5	1,3	1,3		
Contact Resistance	3,6	2,7	2,7	2,4	2,4				
Insulation Resistance		3,8	3,8						
Dielectric Withstanding Voltage		4,9	4,9						
Mechanical shock		6							
Card Retention Force	2,5								
Insertion/Ejection Force	2,5								
Durability	4								
Vibration		5							
Humidity			6						
Salt Water Spray				3					
Temperature Life					3				
Thermal Shock (Temperature rise)			5						
Solderability						2			
Resistance to Reflow Soldering heat							2		
Sample QTY.	5	5	5	5	5	5	5		



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Revision details:							
Revision	Information	Page	Release Date				
0.1	Draft specification	-	01/11/2022				
0.2	Update thermal shock test condition	4	21/11/2022				
А	First public release	-	22/11/2022				

